# Force, torque and pressure sensors

**Industrial Control** 

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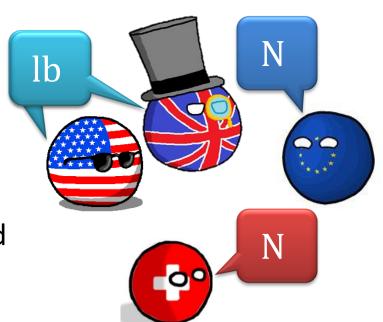


#### Force

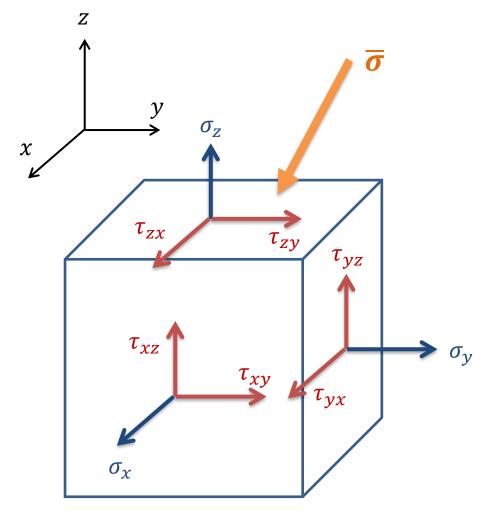
- What do we know about force?
  - a force is an interaction which causes an object with mass to change its velocity
  - SI base unit
  - vector quantity

## **Units**

- Newton N
  - 1N is the force which accelerates a mass of 1kg by 1 m/s<sup>2</sup>
- Pound lb, lbf
  - 1 lb is the force which accelerates a mass of 1 slug by 1 ft/s<sup>2</sup>
  - 1 lbf is the force exerted by standard gravity on a mass of 1 lbm
  - 1 lb = 4.44822 N
- Kilogramm kg
  - 1 kg is the force exerted by standard gravity on a mass of 1 kg



#### Mechanical stress



Stress:

$$\bar{\sigma} = \frac{\bar{F}}{A} \left[ \frac{N}{m^2}, Pa \right]$$

Normal stress:

$$\sigma_x$$
,  $\sigma_y$ ,  $\sigma_z$ 

• Shear stress:

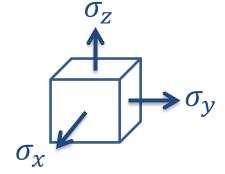
$$\tau_{ij} = \tau_{ji}$$

## Elastic strain caused by normal stress

Up to a limit of stress, a mass is exposed to elastic strain (Hooke's law):

$$\begin{bmatrix} \mathcal{E}_{\chi} \\ \mathcal{E}_{y} \\ \mathcal{E}_{z} \end{bmatrix} = \begin{bmatrix} 1/E & -\nu/E & -\nu/E \\ -\nu/E & 1/E & -\nu/E \\ -\nu/E & -\nu/E & 1/E \end{bmatrix} \begin{bmatrix} \sigma_{\chi} \\ \sigma_{y} \\ \sigma_{z} \end{bmatrix}$$
where

- $\varepsilon_x$  is the relative strain in direction x
- *E* is Young's modulus (silicon: 117GPa, steel: 200GPa)
- $\nu$  is Poisson's ratio  $(\nu \leq 0.5, \text{ silicon: 0.22, steel: 0.3})$

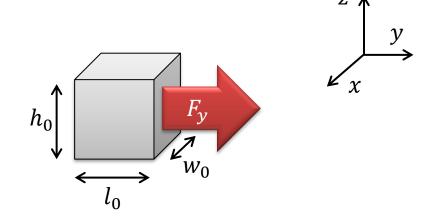


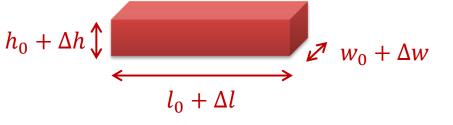
#### Elastic strain

Only normal stress is exerted:

$$\sigma_y = \frac{F_y}{A}$$

- Relative strain:
  - $\varepsilon_y = \frac{\sigma_y}{E}$
  - $\varepsilon_{\chi} = \varepsilon_{Z} = -\frac{\nu \sigma_{y}}{E}$
- Absolute strain:
  - $\Delta l = l_0 \varepsilon_y = l_0 \frac{\sigma_y}{E} > 0$
  - $\Delta w = w_0 \varepsilon_{\chi} = w_0 \frac{-\nu \sigma_{y}}{E} < 0$
  - $\Delta h = h_0 \varepsilon_z = h_0 \frac{-\nu \sigma_y}{F} < 0$





## **Problem**

Give the change of the height and base area of a steel cube with 10 cm edge length if a mass of 100 kg is placed on it. Young's modulus and Poisson-ratio for steel are E = 200 GPa and v = 0.3, respectively.

• 
$$\varepsilon_Z = \frac{\sigma_Z}{E} = \frac{-mg}{A} / E \approx \frac{-1000}{0.1 \cdot 0.1} / (200 \cdot 10^9) = -\frac{10^5}{2 \cdot 10^{11}} = -5 \cdot 10^{-7}$$
  

$$\Delta h = \varepsilon_Z h_0 = -5 \cdot 10^{-7} \cdot 0.1 \text{ m} = -0.05 \mu\text{m}$$

• 
$$\varepsilon_{x} = \varepsilon_{y} = -\frac{v\sigma_{z}}{E} = 1.5 \cdot 10^{-7}$$
  

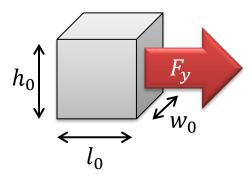
$$\Delta A = (l_{0} + \varepsilon_{x} l_{0}) \cdot (w_{0} + \varepsilon_{y} w_{0}) - l_{0} w_{0} = (0.1 + 0.1 \cdot 1.5 \cdot 10^{-7})^{2} - 0.1^{2} = 2 \cdot 0.1 \cdot 0.1 \cdot 1.5 \cdot 10^{-7} + 2.25 \cdot 10^{-16} \approx 0.003 \text{mm}^{2}$$

## Effect of strain on electrical properties

 Resistance – resistance of a conductor depends on its resistivity, length and diameter

```
• R=
ho rac{l}{A} , where 
ho=1/\sigma \ {
m is the resistivity} \ [\Omega {
m m}], l is the length of the conductor [{
m m}], A is the cross section of the conductor [{
m m}^2]
```

## Geometrical effect of normal strain



$$h_0 + \Delta h \updownarrow \qquad \qquad \swarrow \qquad \qquad \swarrow \qquad \qquad w_0 + \Delta w$$

$$l_0 + \Delta l$$

$$R' = \rho \frac{l'}{A'} = \rho \frac{l_0 + \Delta l}{(w_0 + \Delta w)(h_0 + \Delta h)} = \rho \frac{l_0(1 + \varepsilon_y)}{w_0(1 + \varepsilon_x)h_0(1 + \varepsilon_z)} = \rho \frac{l_0}{A_0} \frac{1 + \varepsilon_y}{(1 + \varepsilon_x)(1 + \varepsilon_z)}$$

- $\varepsilon_x = \varepsilon_z \Rightarrow (1 + \varepsilon_x)(1 + \varepsilon_z) = 1 + \varepsilon_x + \varepsilon_z + \varepsilon_x \varepsilon_z = 1 + 2\varepsilon_x + \varepsilon_x^2 = 1 2\nu\varepsilon_y + \nu^2\varepsilon_y^2$
- $\varepsilon_y \ll 1, \nu < 1 \Rightarrow 1 2\nu\varepsilon_y + \nu^2\varepsilon_y^2 \approx 1 2\nu\varepsilon_y$
- $\frac{1}{1-2\nu\varepsilon_y} = \frac{1+2\nu\varepsilon_y}{1-(2\nu\varepsilon_y)^2} \approx 1+2\nu\varepsilon_y$

$$\Rightarrow R' \approx \rho \frac{l_0}{A_0} (1 + \varepsilon_y) (1 + 2\nu \varepsilon_y) \approx \rho \frac{l_0}{A_0} (1 + \varepsilon_y (1 + 2\nu))$$

## Piezoresistive effect

- Mechanical stress modifies inter-atomic spacing which results in change of the resistivity
- For isotropic effects, the change reads

$$\frac{\Delta \rho}{\rho} = \begin{bmatrix} \pi_{11} & \pi_{12} & \pi_{12} \\ \pi_{12} & \pi_{11} & \pi_{12} \\ \pi_{12} & \pi_{12} & \pi_{11} \\ & & & \pi_{44} \end{bmatrix} \begin{bmatrix} \sigma_{\chi} \\ \sigma_{y} \\ \sigma_{y} \\ \sigma_{xy} \\ \tau_{xy} \\ \tau_{yz} \\ \tau_{zx} \end{bmatrix}$$

 $\pi_{ij}$  piezoresistive coefficients, for metals  $\pi_{44}=0$ 

## Piezoresistive effect

Simplified formula:

$$\frac{\Delta \rho}{\rho} = \pi_l \sigma_l + \pi_t \sigma_t,$$

where  $\pi_l$  adn  $\pi_t$  are the longitudinal and transversal (relative to the direction of current flow) piezoresistive coefficients:

$$\pi_{l,NiCr} \approx 10^{-3} \frac{1}{\text{GPa}}, \pi_{l,Si} \approx 10^{-1} \frac{1}{\text{GPa}}$$

• Omitting the transversal effect:  $rac{\Delta 
ho}{
ho} = \pi_l arepsilon_l E$ 

## Joint effect of mechanical stress

$$R' = (\rho_0 + \Delta \rho) \frac{l_0}{A_0} \left( 1 + \varepsilon_y (1 + 2\nu) \right) =$$

$$\rho_0 \left( 1 + \frac{\Delta \rho}{\rho_0} \right) \frac{l_0}{A_0} \left( 1 + \varepsilon_y (1 + 2\nu) \right) =$$

$$\rho_0 \frac{l_0}{A_0} \left( 1 + \varepsilon_y \pi_l E \right) \left( 1 + \varepsilon_y (1 + 2\nu) \right)$$

$$\varepsilon_y^2 \approx 0 \Rightarrow R' \approx R_0 (1 + \varepsilon_y (E\pi_l + 1 + 2\nu))$$

$$\Delta R = R' - R_0 = R_0 \varepsilon (E\pi_l + 1 + 2\nu)$$

# Gauge factor

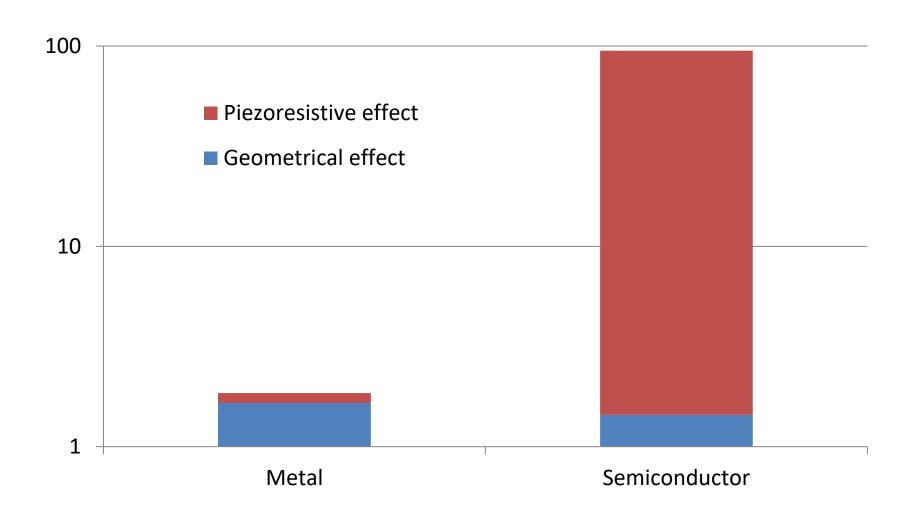
• 
$$\Delta R = R_0 \varepsilon (E \pi_l + 1 + 2\nu)$$

• 
$$g = GF = \frac{\Delta R/R}{\Delta l/l} = \frac{\Delta R/R}{\varepsilon} = E\pi_l + 1 + 2\nu$$
 [1]

Gauge factor is a unitless quantity describing the ratio of relative elastic strain and relative change of resistance

- $R = R_0(1 + g\varepsilon)$
- Value of gauge factor
  - for metals: 2 ... 5
  - for semiconductors: 125 ... 200 (depends on doping)

# Components of the gauge factor

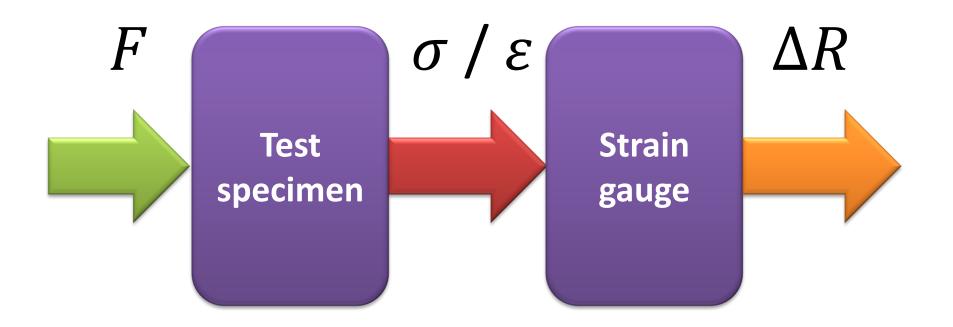


## Effect of shear strain

- Piezoresistive effect might change the resistivity if shear strain is exerted
- No effect of shear strain for metals ( $\pi_{44} = 0$ )
- For semiconductors the effect of shear strain can be significant

## Strain gauges

(strain gages)



Dynamical transducer up to a few kHz frequency

#### Magnitude of change in resistance

- Metal strain gauges
  - maximal strain:  $\varepsilon_{max} \approx \pm 0.2\% \dots \pm 2\%$
  - gauge factor:  $g \approx 2 5$
  - $\Delta R = g\varepsilon < 10\%$ , typically  $\Delta R \approx 1 \dots 5\%$
- Semiconductor strain gauges
  - maximal strain:  $\varepsilon_{max} \approx \pm 0.5\%$
  - gauge factor:  $g \approx 125 200$
  - $\Delta R = g \varepsilon > 50\%$ , up to 100%
- Change of resistance limited by the maximal strain of the test specimen!
  - steel: ca. 0.12%
  - aluminum: ca. 0.35%

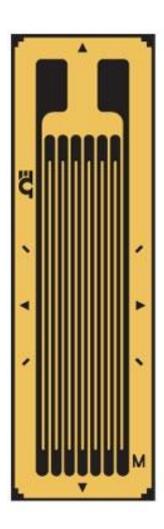
# Attachment of strain gauges

- Bond between the strain gauge and the test specimen is of paramount importance: strains of the gauge and the test specimen should be the same
- Strain gauge: resistance layer (metal or semiconductor) on insulated backing
- Attachment by gluing
- Principle cause of error: crawling due to different thermal expansion properties of the test specimen, the strain gauge and the glue
- Use of a special glue is strongly recommended

# Metal foil strain gauges

- Goal: high resistance with small footprint
- Solution: zig-zag pattern
- Great sensitivity for strain in the principal direction
- Non-zero transversal sensitivity:

$$g_t = K_t g$$
, where typically  $K_t < 1\%$ 



## Metal foil strain gauges

**Backing** insulation attachment (by glue) typical material: epoxy Metal foil resistance pattern Lead or solder pad Optional external enclosure (rare)

# Strain gauge alloys

- Constantan (Cu-Ni)  $g \approx 2$ 
  - low cost
  - thermal expansion can be set by alloying
  - wide linear range
  - ideal for generic use
  - Irreversible change in properties at high temperature
- Karma (K-alloy, Ni-Cr, Nichrome)  $g \approx 2 2.4$ 
  - exceptional linerarity
  - high accuracy and sensitivity
  - high stability
  - wide temperature range:  $-269 ... + 260 \,^{\circ}$ C

# Strain gauge alloys

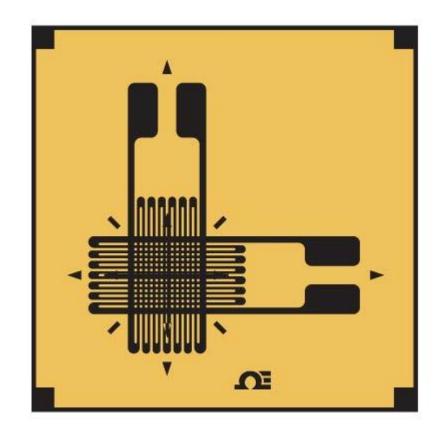
- Platinum alloys  $g \approx 4 5$ 
  - wide temperature range
  - exceptional stability
  - high piezoresistive effect
  - high cost
- Isoelastic  $g \approx 3.5$ 
  - for measurement of dynamic strain
  - high thermal expansion, sensitive for temperature change

## Parameters of metal foil strain gauges

- Base resistance:  $90 120 350 600 1000 \Omega$
- Size (length): 1.5 ... 50 mm
- Thickness: few microns
- Gauge factor: 2 ... 5
- Elasticity (bending radius): ca. 1/10 of the length
- Accuracy
  - base resistance:  $\pm 0.1 1\%$
  - gauge factor: varies with batch

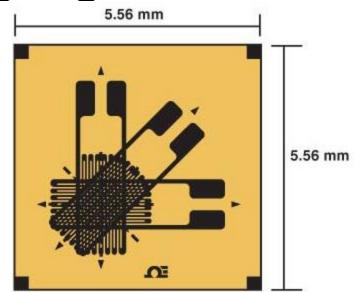
# Biaxial (Tee) strain gauges

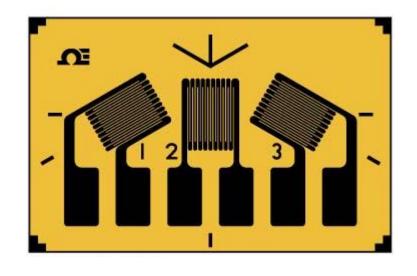
- Two zig-zag patterns in orthogonal configuration
- For measurement of stress if principal directions are known and no shear stress is present



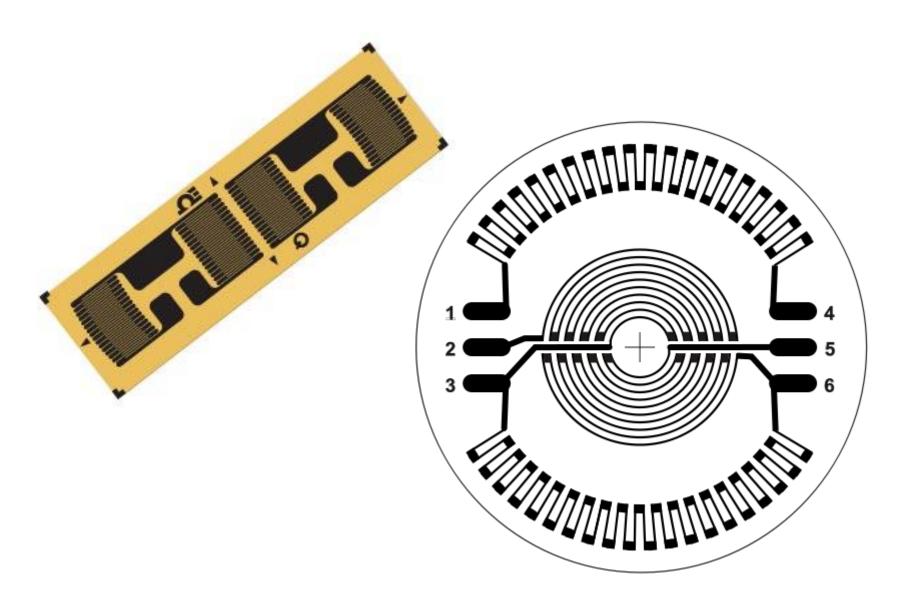
## Rosette strain gauges

- Suitable for stress measurement on a plane
  - 3 strains
  - 3 components (normal strains and shear strain)
- Zig-zag configurations
  - beside or over each other (in different layers)
  - Angles of 45° or 60°





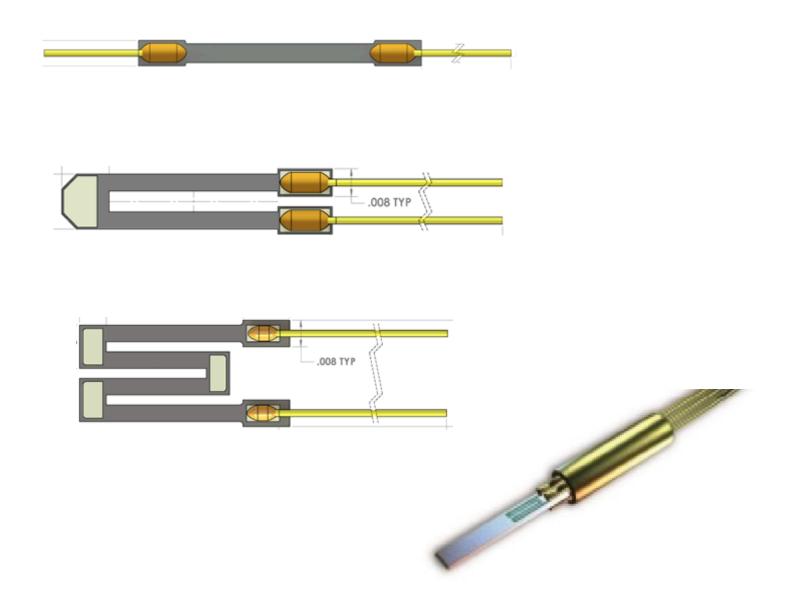
# Special strain gauges



## Semiconductor strain gauges

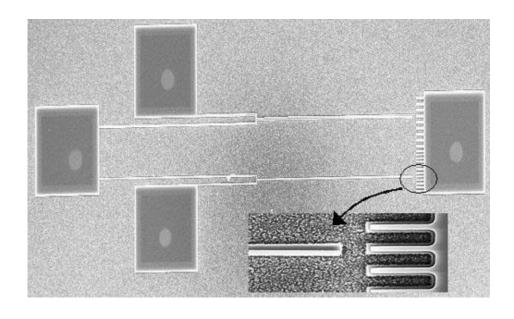
- Doped single crystal or polycrystalline (Si, Ge)
- Base resistance can be set by doping
- No need for complex zig-zag patterns
- High gauge factor
  - single crystal:  $q \approx -100 +200$
  - polycrystalline:  $g \approx 30 45$
- No need for backing
- Sensitive for multiple normal strains and shear strain
- High temperature sensitivity
- Rigid
- High cost

# Semiconductor strain gauges

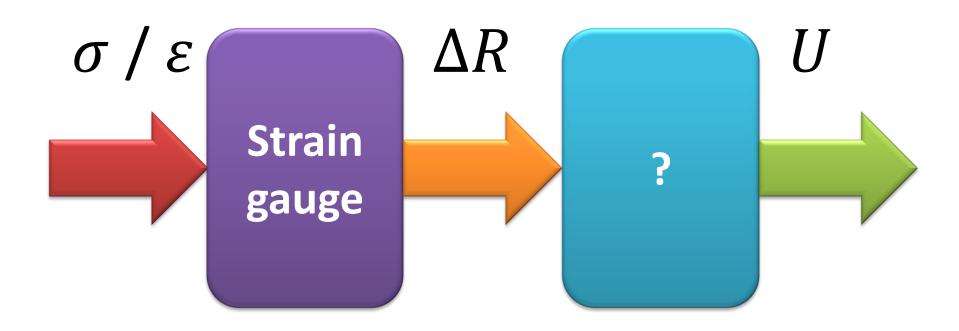


# Semiconductor strain gauges

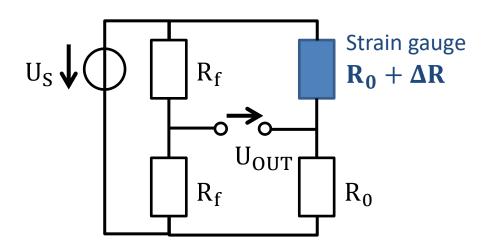




# Measurement circuitry for strain gauges



# Simple bridge circuit



$$U_{OUT} = \frac{U_S}{2} - U_S \frac{R_0}{R_0 + (R_0 + \Delta R)} = U_S \frac{(2R_0 + \Delta R) - 2R_0}{2(2R_0 + \Delta R)} = U_S \frac{\Delta R}{2(2R_0 + \Delta R)} \approx$$

$$\approx U_S \frac{\Delta R}{4R_0} = \frac{U_S}{4} g \varepsilon$$

## Thermal effect

• As for metal RTDs, resistance depends on the temperature by  $R \approx R_0(1+\alpha(\vartheta-\vartheta_0))$ , where  $R_0$  is the base resistance at temperature  $\vartheta_0$ ,  $\alpha$  is the temperature coefficient of resistance,  $\vartheta$  is the actual temperature:

$$\frac{\Delta R}{R_0} = \alpha(\vartheta - \vartheta_0) = \alpha \Delta \vartheta$$

Thermal effect is considered as a virtual strain:

$$\varepsilon = \frac{1}{g} \frac{\Delta R}{R_0} = \frac{\alpha}{g} (\vartheta - \vartheta_0) = \frac{\alpha}{g} \Delta \vartheta$$

# Thermal effect - problem

Temperature of a constantan strain gauge is increased by  $10^{\circ}$ C. How much is the virtual strain caused by the thermal effect?

For a constantan strain gauge  $\alpha = 3 \cdot 10^{-5} \text{ 1/°C}$ , g = 2

Virtual strain:

$$\varepsilon = \frac{\alpha}{g}(\vartheta - \vartheta_0) = \frac{3 \cdot 10^{-5}}{2} \cdot 10 = 0.015\%$$

Full scale error if the maximal strain is  $\varepsilon_{max} = 1\% = 10^{-2}$ :

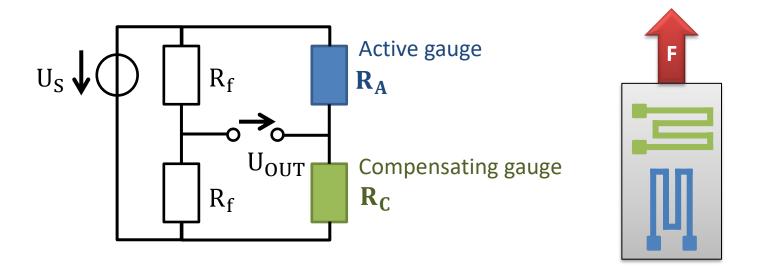
$$\frac{0.015}{1} = 0.015 = \mathbf{1.5}\%_{FS}$$

## Compensation of thermal effect

- What kind of device shall we use for compensation?
  - a resistor with same base resistance
  - a resistor with same temperature coefficient

- Use an identical strain gauge!
  - no stress should be exerted
  - if not applicable, the stress should be transversal

# Compensation of thermal effect



• If only transversal effect is exerted on the compensating gauge:  $R_C = R_0(1 + gK_t\varepsilon)(1 + \alpha\Delta\theta)$ 

• 
$$U_{OUT} = \frac{U_T}{2} \frac{R_A - R_C}{R_A + R_C} = \frac{U_T}{2} \frac{R_0 (1 + g\varepsilon)(1 + \alpha\Delta\vartheta) - R_0 (1 + gK_t\varepsilon)(1 + \alpha\Delta\vartheta)}{R_0 (1 + g\varepsilon)(1 + \alpha\Delta\vartheta) + R_0 (1 + gK_t\varepsilon)(1 + \alpha\Delta\vartheta)}$$

# Compensation of thermal effect

• 
$$U_{OUT} = \frac{U_S}{2} \frac{R_0(1+g\varepsilon)(1+\alpha\Delta\vartheta) - R_0(1+gK_t\varepsilon)(1+\alpha\Delta\vartheta)}{R_0(1+g\varepsilon)(1+\alpha\Delta\vartheta) + R_0(1+gK_t\varepsilon)(1+\alpha\Delta\vartheta)} = \frac{U_S}{2} \frac{(1+g\varepsilon) - (1+gK_t\varepsilon)}{(1+g\varepsilon) + (1+gK_t\varepsilon)} = \frac{U_S}{2} \frac{g\varepsilon - gK_t\varepsilon}{2 + g\varepsilon + gK_t\varepsilon} = \frac{U_S}{2} \frac{g\varepsilon(1-K_t)}{2 + g\varepsilon(1+K_t)}$$

• Simplification:  $0 \le K_t \le 0.1$ , hence

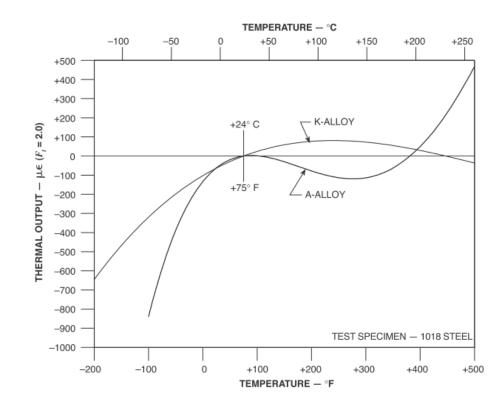
$$(1 + K_t) \approx (1 - K_t) \approx 1, g\varepsilon \ll 1$$

$$\Rightarrow \mathbf{U}_{OUT} = \frac{U_S}{2} \frac{g\varepsilon}{2 + g\varepsilon} \approx \frac{U_S}{2} \frac{g\varepsilon}{2} = \frac{\mathbf{U}_S}{4} g\varepsilon$$

- Output voltage is
  - temperature-independent
  - nearly linear function of the strain

## Self-compensating gauges

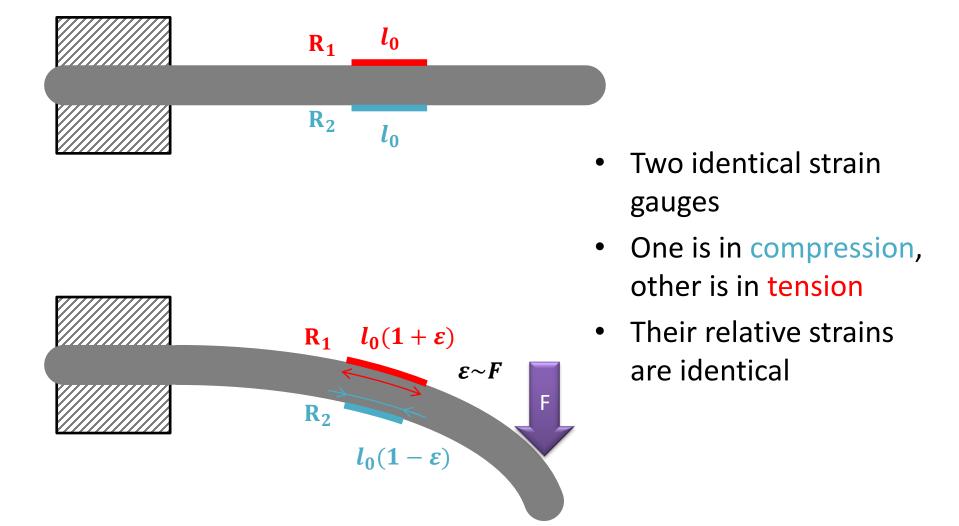
- Problem: thermal extension of the test specimen causes strain, which is considered as effect of an external force
- Self temperature-compensation: temperature dependent resistivity of specific alloys compensate thermal expansion in the most frequently used temperature range
- Various alloys for test specimens of different materials



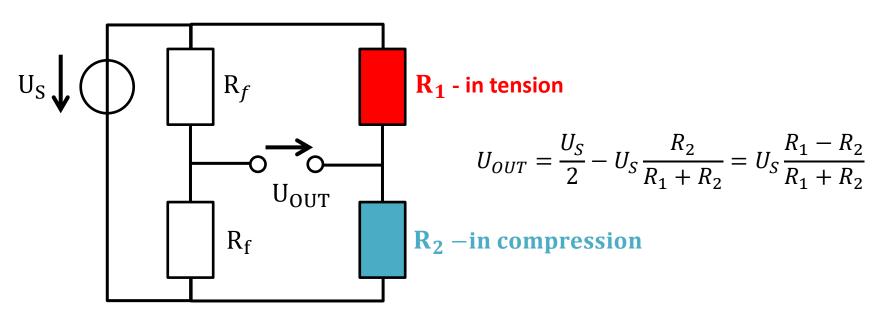
### Self-heating

- Strain gauges are resistors, hence self-heating effect is present
- Like metal RTDs the current used for measurement shall be the lowest possible (magnitude: mA)

# Two active gauge configuration (half bridge)



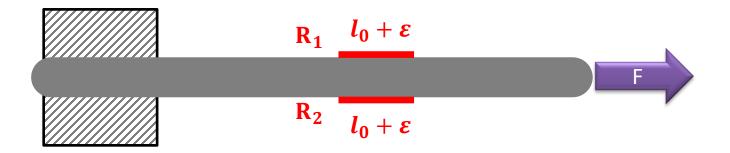
# Two active gauge configuration (half bridge)



$$\boldsymbol{U_{OUT}} = \frac{U_S}{2} \frac{R_1 - R_2}{R_1 + R_2} = \frac{U_S}{2} \frac{R_0 (1 + \alpha \Delta \vartheta)(1 + g\varepsilon) - R_0 (1 + \alpha \Delta \vartheta)(1 - g\varepsilon)}{R_0 (1 + \alpha \Delta \vartheta)(1 + g\varepsilon) + R_0 (1 + \alpha \Delta \vartheta)(1 - g\varepsilon)} = \frac{U_S}{2} \frac{2g\varepsilon}{2} = \frac{\boldsymbol{U_S}}{2} \boldsymbol{g\varepsilon}$$

By using two active gauges the sensitivity is doubled, output voltage is temperature-independent and is a linear function of the strain.

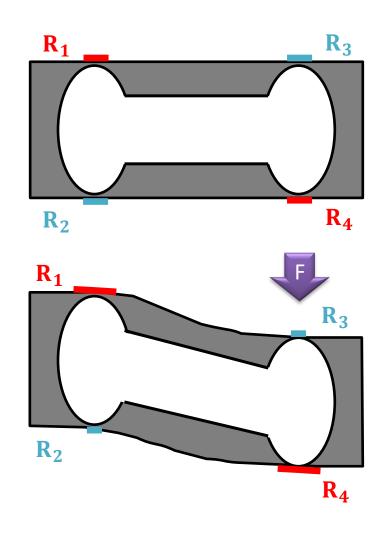
# Two active gauge configuration (half bridge)



• 
$$U_{OUT} = \frac{U_S}{2} \frac{R_1 - R_2}{R_1 + R_2} = 0$$

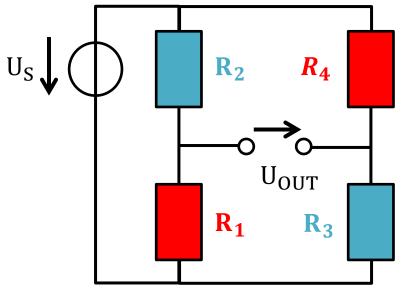
- Configuration is sensitive to bending force only (not to tension force)
- Tension force can be measured by using one of the gauges

# Four active gauge configuration (full bridge)



- Four identical strain gauges
- $R_2$  and  $R_3$  in compression,  $R_1$  and  $R_4$  in tension
- Relative strains of the four gauges are identical

# Four active gauge configuration (full bridge)



 $R_1, R_4$ : in tension

 $R_2$ ,  $R_3$ : in compression

$$U_{OUT} = U_S \frac{R_1}{R_1 + R_2} - U_S \frac{R_3}{R_3 + R_4} = U_S \frac{R_1 - R_2}{R_1 + R_2} =$$

$$=U_{S}\frac{R_{0}(1+\alpha\Delta\vartheta)(1+g\varepsilon)-R_{0}(1+\alpha\Delta\vartheta)(1-g\varepsilon)}{R_{0}(1+\alpha\Delta\vartheta)(1+g\varepsilon)+R_{0}(1+\alpha\Delta\vartheta)(1-g\varepsilon)}=U_{S}g\varepsilon$$

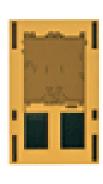
By using four active gauges the sensitivity is increased by a factor or four, output voltage is temperature-independent and is a linear function of the strain.

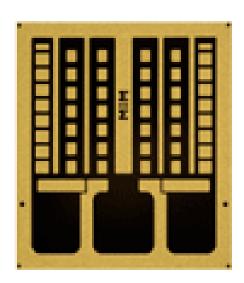
#### Fine tuning of bridge cicruits

- Bridge circuits suffer from various problems:
  - thermal offset error caused by thermal expansion and manufacturing variance of gauges
  - unbalanced bridge due to manufacturing variance of gauges
  - thermal effect on sensitivity caused by temperaturedependence of Young's modulus and gauge-factor
- Output span (cell factor) should be set to a prescribed value

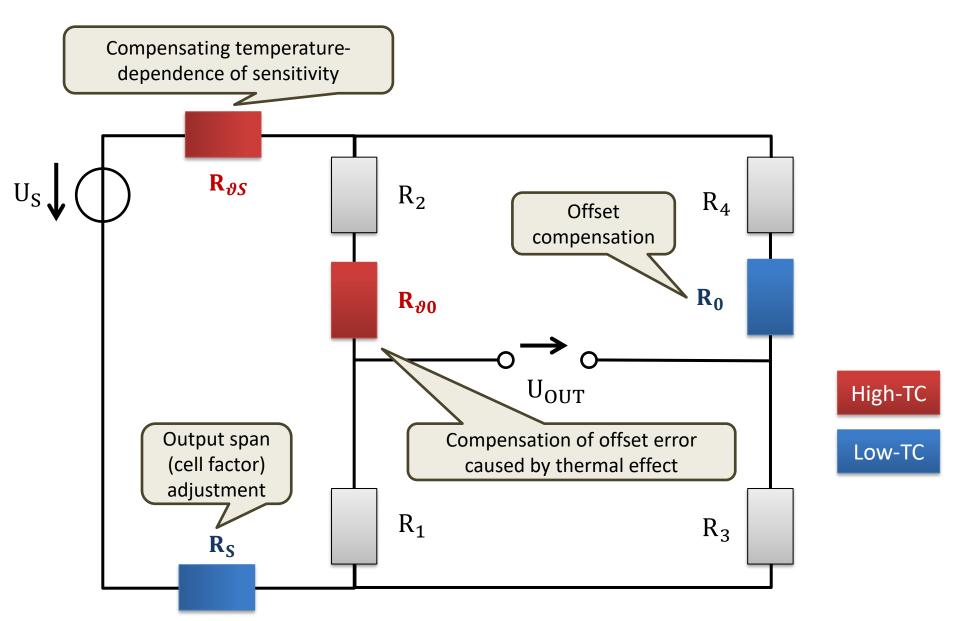
### Fine tuning of bridge circuits

- Bridges are tuned by resistors with high and low temperature coefficient ("high-TC" and "low-TC" resistors)
- Special resistors similar to strain gauges
- Resistor value can be trimmed by the user (trimmable ladder pattern)

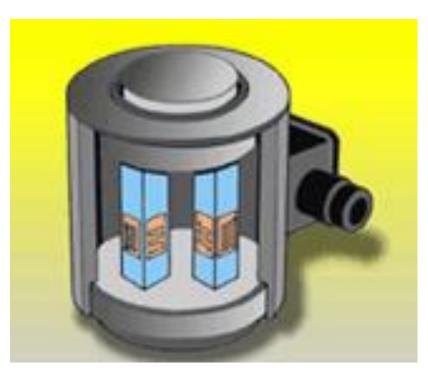




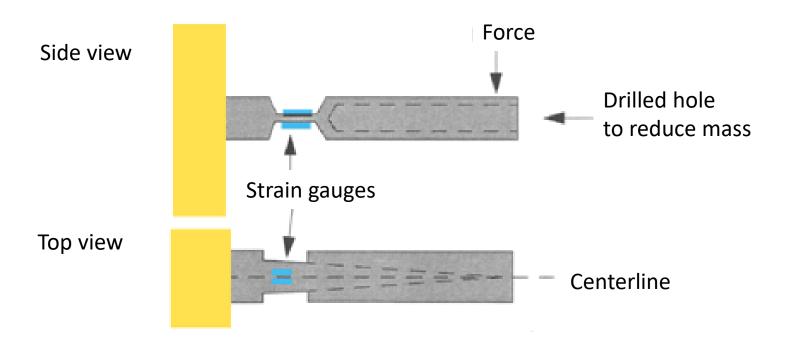
### Fine tuning of bridge circuits



- Test specimen, strain gauges and bridge circuit integrated to a single device
- Most important features of the test specimen
  - strain can be related unambiguously (preferably in a linear way) to mechanical stress
  - strain is elastic in the desired measurement range
  - high stability

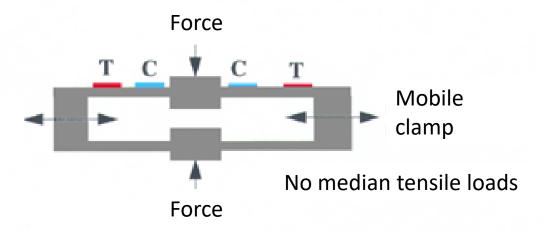


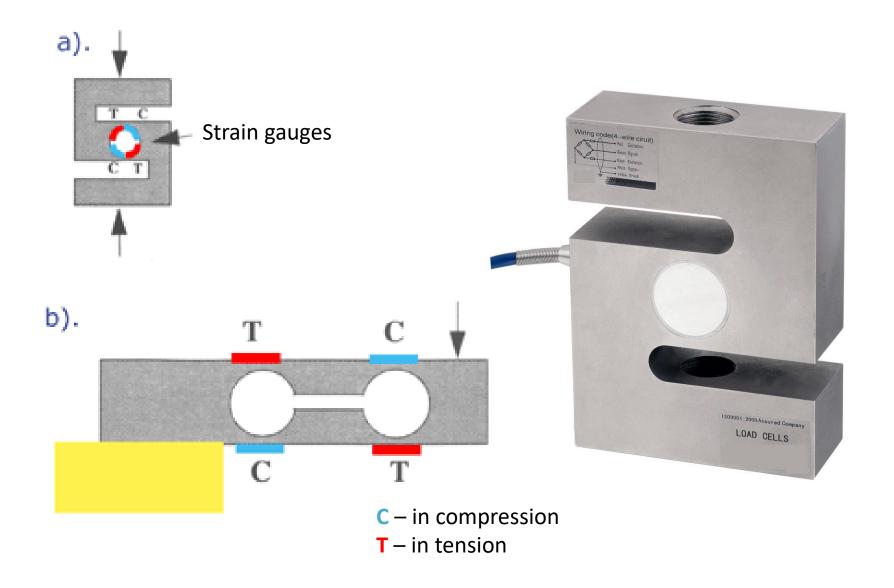


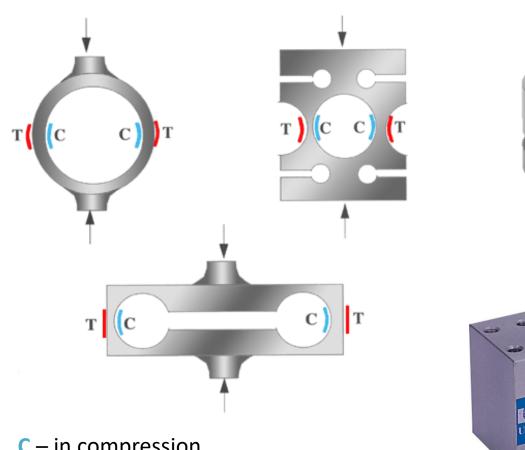




Median tensile loads are present



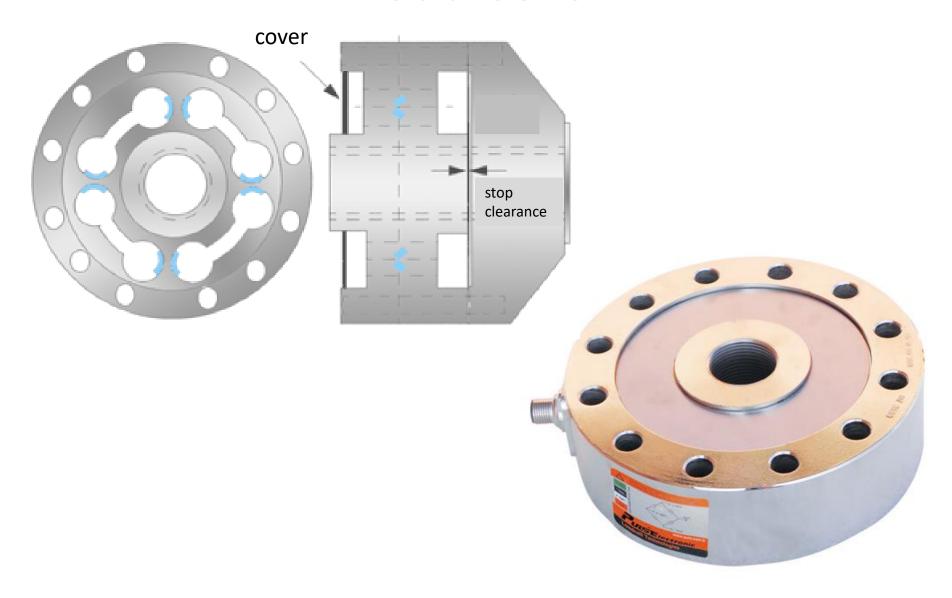


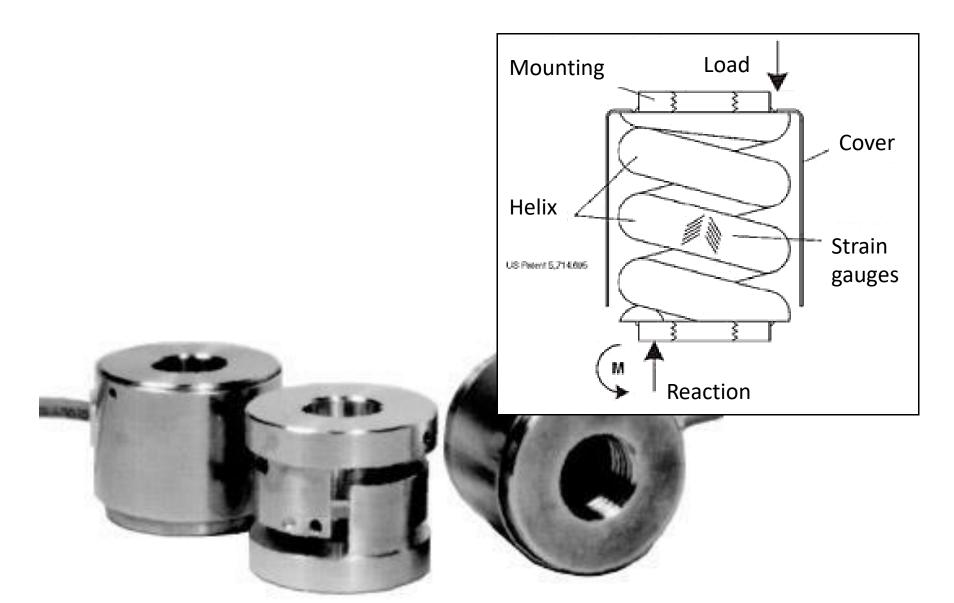


**C** – in compression

T – in tension

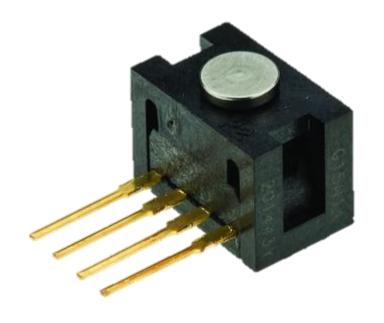






#### MEMS load cells

- In silico micro-manufactured load cell
- Small size
- Narrow measurement range
- Sensitive to overload



#### Cell factor

- Consider linear output voltage, i.e.  $U_{OUT}=U_S a F$ , where a is a device-specific constant
- Cell factor:

$$C = \frac{U_{OUT}}{U_S} \bigg|_{F = F_{max}} = \frac{U_{FS}}{U_S} \text{ [mV/V]}$$

Output voltage corresponding to a force F:

$$U_{OUT} = C \cdot U_S \cdot \frac{F}{F_{max}}$$

• Force corresponding to output voltage  $U_{OUT}$ :

$$F = F_{max} \frac{1}{C} \frac{U_{OUT}}{U_S}$$

### Cell factor - problem

A load cell contains four constantan strain gauges (g=2), its maximal load is  $10 \, \mathrm{kg}$ , causing a strain of  $\varepsilon_{max} = 0.1\%$  for each gauge. Give the cell factor of the load cell. Give the output voltage for a load of  $2.5 \, \mathrm{kg}$  if the supply voltage is  $U_S=24 \, \mathrm{V}$ .

- Output voltage of the bridge:  $U_{OUT} = U_S g \varepsilon$
- Output voltage corresponding to maximal load:

$$U_{FS} = U_S g \varepsilon_{max} = 0.002 U_S$$

• Cell factor:

$$C = \frac{U_{FS}}{U_S} = 2\text{mV/V}$$

Output voltage for 2.5 kg load with 24V supply voltage:

$$U_{OUT} = C \cdot U_S \cdot \frac{F}{F_{max}} = 0.002 \cdot 24 \cdot 0.25 = 12 \text{mV}$$

#### Cell factor - problem

Maximal load of a load cell is 5kg, its cell factor is  $C=1\,\text{mV/V}$ , the supply voltage is  $U_S=2.5\text{V}$ . Give the actual force applied if the output voltage of the cell is  $U_{OUT}=0.25\text{mV}$ ?

- Output voltage of the cell:  $U_{OUT} = U_S C \frac{F}{F_{max}}$
- Actual force:

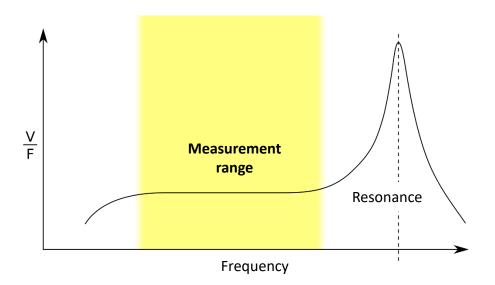
$$F = F_{max} \frac{1}{C} \frac{U_{OUT}}{U_S} = 5 \text{ [kg]} \cdot \frac{1}{0.001 \text{[V/V]}} \cdot \frac{0.00025 \text{ [V]}}{2.5 \text{ [V]}} = 0.5 \text{ kg}$$

Values above are actual parameters of a low-cost load cell with 5 kg maximal load; force exerted corresponds to the weight of an 500 ml plastic bottle filled with water

### Piezoelectric strain gauges

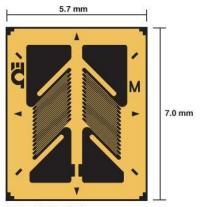
- Piezoelectric materials produce electrical voltage when exposed to mechanical stress (and vice versa)
- Problem: voltage vanishes quickly
- Applicable for measurement of dynamic stress only





#### Torque measurement with strain gauges

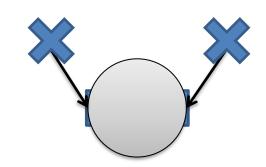
- Elastic torsion of the shaft exerts shear stress in 45° direction
- Strain due to stress can be measured by  $2 \times 2$  strain gauges
- Problem: need of slip ring connection to the rotating shaft



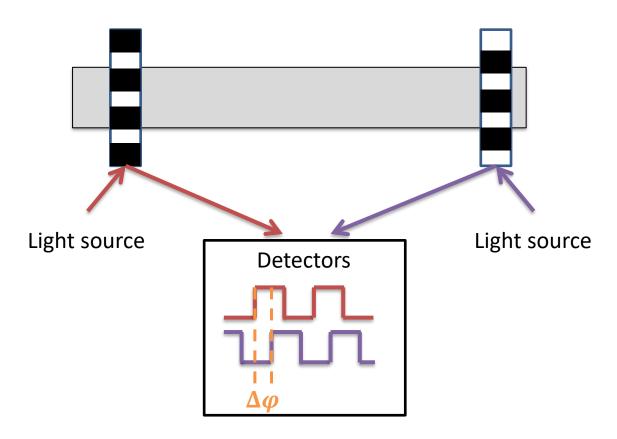








#### Optical torque sensors



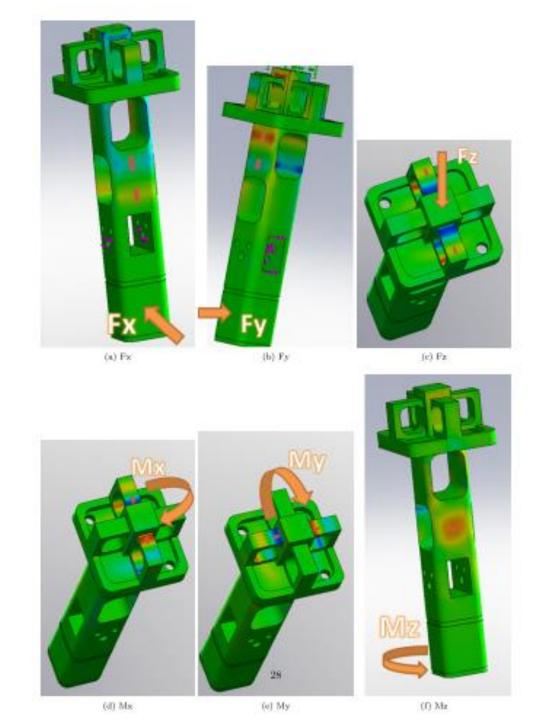
- Torsion of shaft is related directly to the torque
- No active (electrically powered) elements located on the shaft, phase shift can be measured easily

# 6-DOF force and torque sensors



#### Quantities measured:

- force along three axis
- torques around three axis



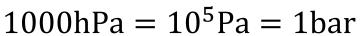
#### **Pressure - Units**

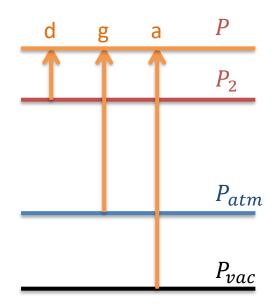
- Pascal Pa
  - 1 Pa =  $1 \text{ N/m}^2$
- Bar bar
  - $10^6 \text{ dyn/cm}^2$ , azaz  $10^6 \cdot 10^{-5} \text{N}/10^{-4} \text{m}^2$
  - $1 \text{ bar} = 10^5 \text{Pa} = 100 \text{kPa}$
- Pounds per square inch psi
  - $1 \text{ psi} = 1 \text{ lb/inch}^2$
  - 1 bar  $\approx$  14.5 psi
- Other units
  - 1 atm  $\approx 1.013 \cdot 10^5 Pa$
  - 1 Hgmm (torr) ≈ 133.3224 Pa



#### Types of pressure scale

- Differential pressure, [psid]
  - referenced to another arbitrary pressure
- Gauge pressure, [psig]
  - referenced to atmospheric pressure
  - atmospheric pressure in Hungary ca.





- Absolute pressure, [psia]
  - referenced to full vacuum

#### Non-electric pressure sensors

- Tube membrane
- Bourdon-tube
  - high accuracy
  - still used as near-field gauge



## Principle of pressure sensing

- Pressure: force / surface
- Therefore, we shall measure force (if surface is known)
- Atmospheric pressure is ca.  $10^5 Pa = 10 N/cm^2$
- We shall either use a sensor of large surface or one with elastic sensing element

## Principle of pressure sensing

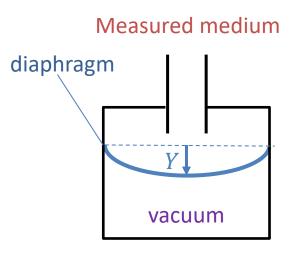
- Test specimen: diaphragm (membrane)
- Circle or square shaped, partially elastic disc clamped at its circumference
- Diaphragm deflects when exposed to pressure

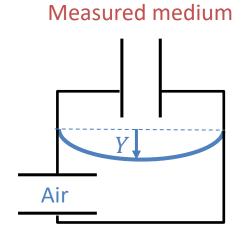


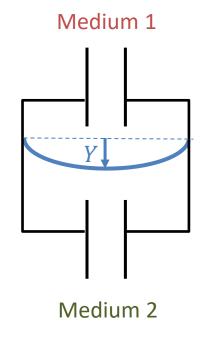




### Principle of pressure sensing







$$Y \propto P_m$$

$$Y \propto P_m - P_{atm}$$

Gauge pressure (referenced to atmospheric pressure)

$$Y \propto P_{m1} - P_{m2}$$

Differential pressure (referenced to medium 2)

## Deflection of the diaphragm

#### Radial

• 
$$\varepsilon_{RC} = \frac{3PR_0^2(1-\nu^2)}{8t^2E}$$
  
•  $\varepsilon_{R0} = \frac{3PR_0^2(1-\nu^2)}{4t^2E}$ 

• 
$$\varepsilon_{R0} = \frac{3PR_0^2(1-v^2)}{4t^2E}$$

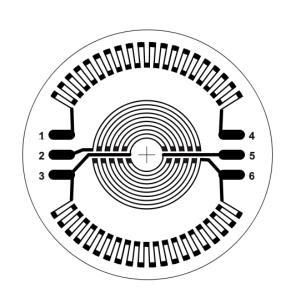
#### Tangential

• 
$$\varepsilon_{TC} = \frac{3PR_0^2(1-\nu^2)}{8t^2E}$$
  
•  $\varepsilon_{T0} = 0$ 

• 
$$\varepsilon_{T0} = 0$$

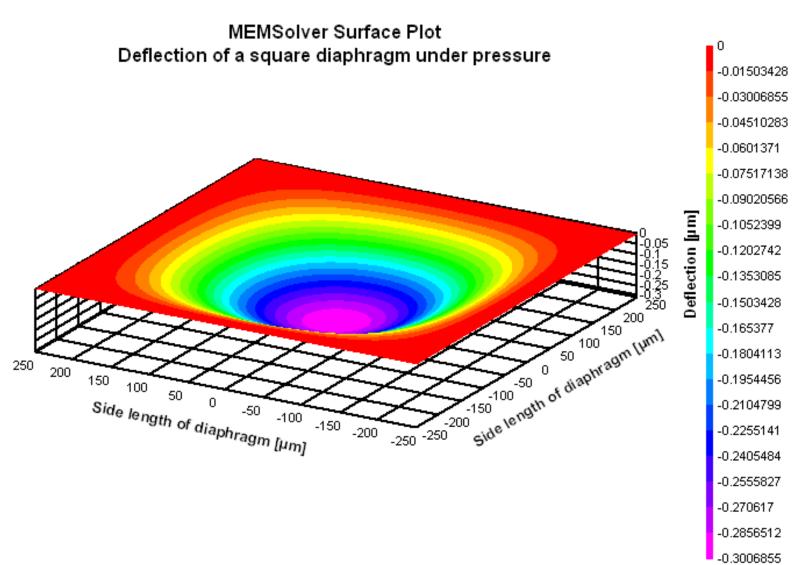
#### Displacement of the center

• 
$$Y_C = \frac{3PR_0^4(1-\nu^2)}{16t^3E^2}$$



- *RC/TC*: at center
- R0/T0: around circumference
- P: pressure (Pa)
- $R_0$ : diaphragm radius (mm)
- $\nu$ : Poisson ration
- t: diaphragm thickness (mm)
- E: Young's modulus (Pa)

### Deflection of the diaphragm



#### Deflection of the diaphragm

- For small deflections pressure is proportional to the deflection of the elastic diaphragm (deflection is a linear function of pressure)
- What is considered as small deflection?
  - rule of thumb: not greater than the thickness of the diaphragm
  - to ensure linearity error of 0.3%: quarter of diaphragm thickness
- When the diaphragm can be considered as elastic?
  - rule of thumb: if radius is at least 200 times the thickness.
  - elasticity of diaphragm decreases linearity error
- If strain gauges are used for the measurement, maximal strain of the diaphragm must not be greater than the maximal strain of the gauge
- For strain gauge pressure sensors, the magnitude of maximal deflection is  $1\mu m$

# Strain-based measurement of diaphragm deflection

- Bonded strain gauge
- Thin-film strain gauge
- Thick-film strain gauge
- Integrated (piezoresistive, semiconductor) strain gauge

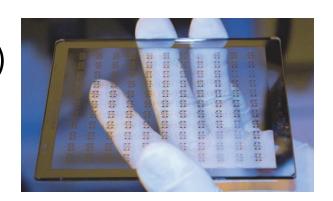
### Bonded strain gauge sensors

- Significant drift
- High mechanical wear of strain gauge
- Low reliability



### Metal thin-film diaphragms

- Backing
  - stainless steel
  - tantal, special alloys (Hastelloy, Inconel)
  - silver (for chloride and fluoride media)
- Layer deposition
  - insulation layer
  - resistor layer
- Zig-zag pattern on side not exposed to medium formed by photolithography
- Not suitable for small pressures
- Can withstand large pressures
- Stable, insensitive for mechanical vibration



#### Ceramic thick-film sensors

- Backing: Al<sub>2</sub>O<sub>3</sub>
- Zig-zag pattern applied by screen printing on the side not exposed to the medium
- Corrosion-resistant
- Good long-term stabilty
- Sensitive to burst pressure due to fragility of ceramic





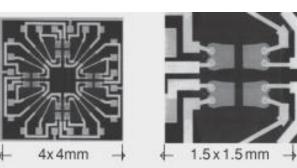
### Strain gauge pressure sensors

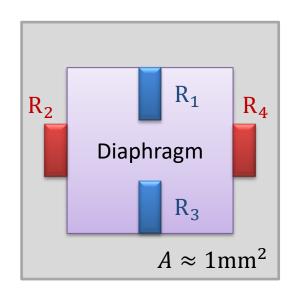
- For measurement of both absolute, gauge and differential pressure
- Measurement range up to 1400 MPa (14 000 bar)
- Accuracy: 0.25%FS
- Long time drift: 0.25%FS / 6 months

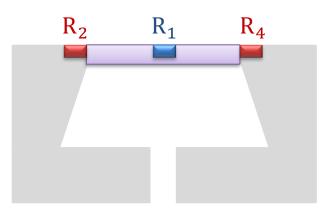
### Piezoresistive pressure sensors

- In-silico diaphragm and strain gauge
- Base structure manufactured by etching
- Strain gauges manufactured by diffusion
- Longitudinal  $(R_1, R_3)$  and transversal  $(R_2, R_4)$  piezoresistive coefficients are of different signs
- In-silico leads and compensation

circuitry

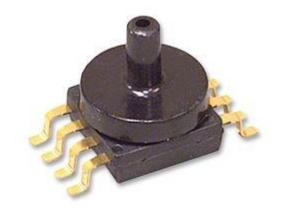






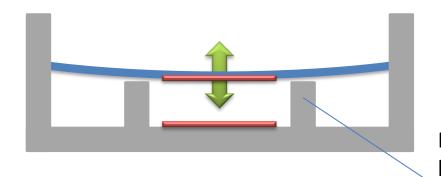
### Piezoresistive pressure sensors

- Fragile devices
  - protection by additional diaphragm
  - isolation from environment
  - silica oil pressure transmission
- Significant thermal effects
- In-silico compensating electronics



### Capacitive pressure sensors

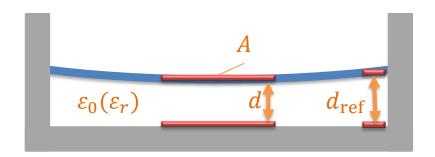
- Membrane and baseplate are plates of a capacitor
- Measurement based not on the deflection of the membrane but on the displacement of its center



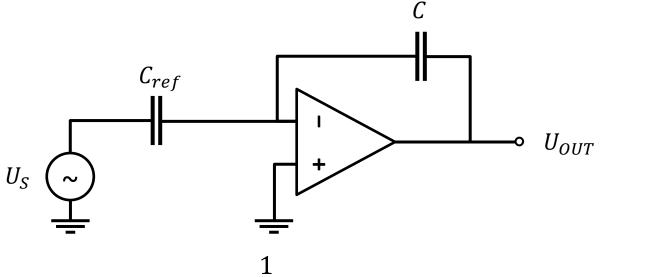
Mechanical deflection barrier: protects the diaphragm in case of overpressure

### Capacitive pressure sensors

- Capacitance:  $C = \varepsilon \frac{A}{d} = \varepsilon_0 \varepsilon_r \frac{A}{d}$
- Displacement is proportional to the pressure
- Measurement range up to 25%
- Reference capacitor
  - at the circumference of the diaphragm (no displacement)
  - distance of plates is constant:  $C_{ref} = \frac{\varepsilon A_{ref}}{d_{ref}} = \text{constant}$



### Capacitance measurement



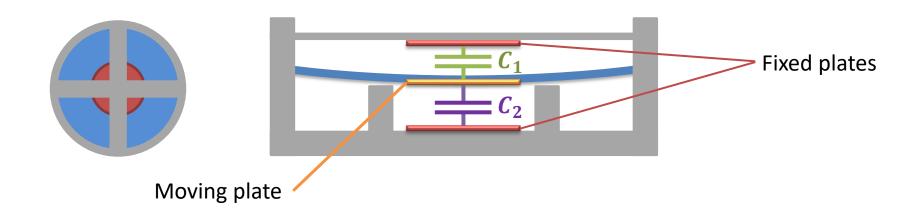
$$U_{OUT} = -U_S \frac{Z}{Z_{ref}} = -U_S \frac{\frac{1}{j\omega C}}{\frac{1}{j\omega C_{ref}}} = -U_S \frac{C_{ref}}{C} = -U_S \frac{C_{ref}}{\epsilon \frac{A}{d}} = -U_S \frac{C_{ref}}{\epsilon A} d$$

- Output is directly proportional to the displacement of the diaphragm center
- Also directly proportional to pressure if displacement is small
- If area of reference capacitor plates is identical to the area of the moving plates (relative permittivities are the same as the dielectric material is the same):

$$U_{\text{OUT}} = -U_S \frac{c_{ref}}{c} = -U_S \frac{\varepsilon A/d_{ref}}{\varepsilon A/d} = -U_S \frac{d}{d_{ref}}$$

### Differential-capacitive pressure sensors

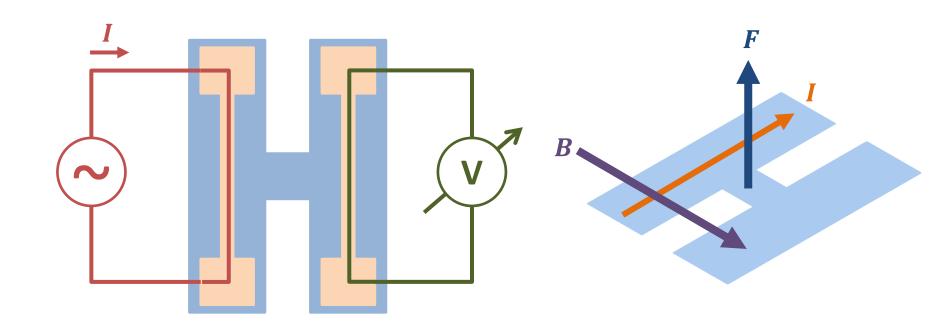
- Membrane is a moving plate between two fixed ones
- Ration  $C_1/C_2$  changes nearly directly proportional to the displacement of diaphragm center
- Displacement can be measured easily (see capacitive displacement sensors)



### Capacitive pressure sensors

- Larger strain allows wider measurement range
- From vacuum up to 700 bars
- Used especially in low-pressure or vacuum applications
- No need for temperature compensation
- Accuracy up to 0.01%FS

## MEMS resonant pressure sensors (Yokogawa DPharp)

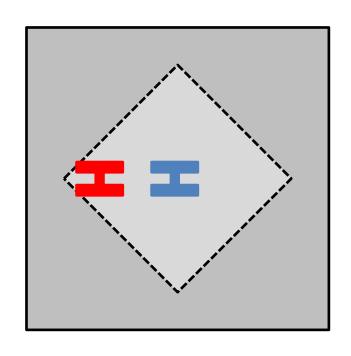


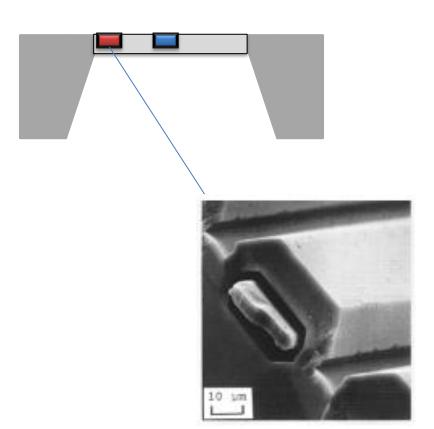
- If excited by alternating current in stationary magnetic field, the H-shaped element resonates (Lorentz force)
- Sinusoidal voltage is induced in the other side of the resonator (Faraday's law)

### Resonating frequency

- The resonator is resonated at its natural frequency by a PLL
- $f^2=c\varepsilon$ , where  $\varepsilon$  is the tensile force, c is a device-specific constant
- $\varepsilon = \varepsilon_0 + \varepsilon_S \pm \varepsilon_{DP}$ 
  - $\varepsilon_0$ : initial tensile force (originates from the structure of the resonator)
  - $\varepsilon_S$ : tensile force due to static pressure (applied to both sides of the resonator)
  - $\varepsilon_{DP}$ : tensile force due to differential pressure (difference of pressure between the two sides)

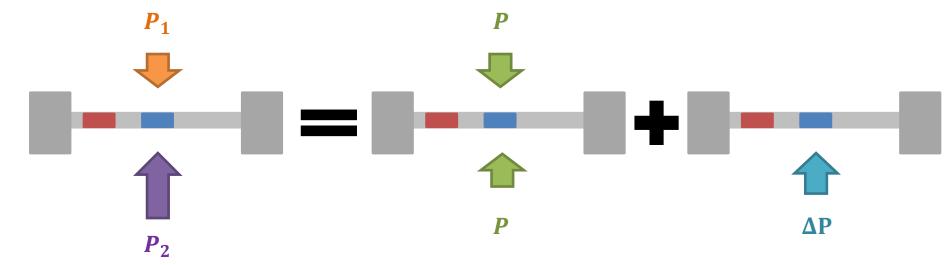
#### Location of resonators





### Pressure components

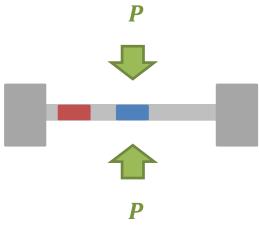
- $P_1 = P$
- $P_2 = P + \Delta P$
- *P*: static pressure (common component of pressure)
- $\Delta P = P_2 P_1 = P_2 P$ : differential pressure

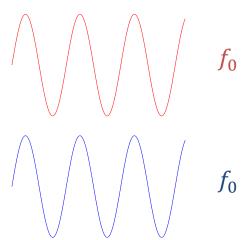


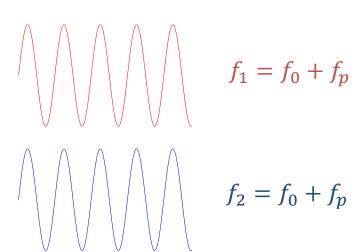
### Static pressure



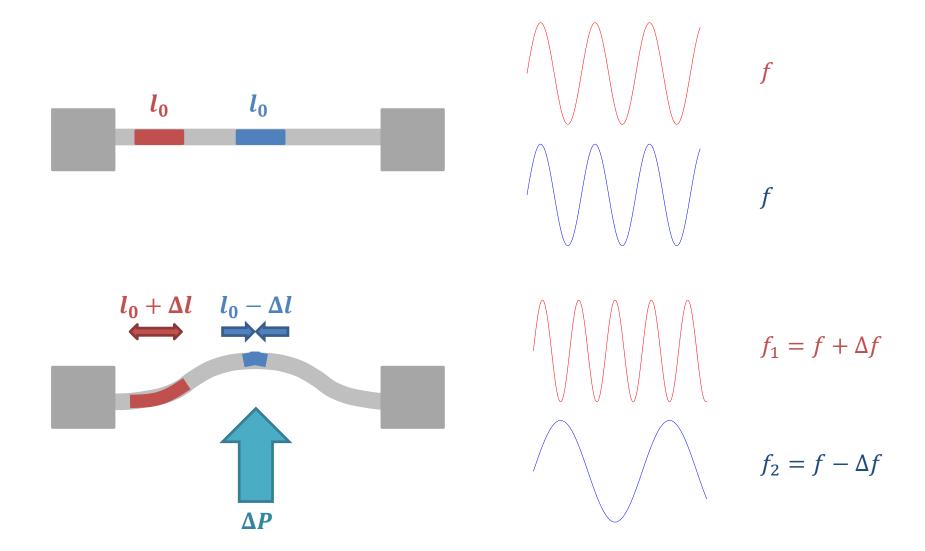
- Pressure increases the tensile force inside the silicon structure
- P increases  $\Rightarrow \varepsilon$  increases  $\Rightarrow f$  increases







### Differential pressure



# Relationship between pressure and frequency

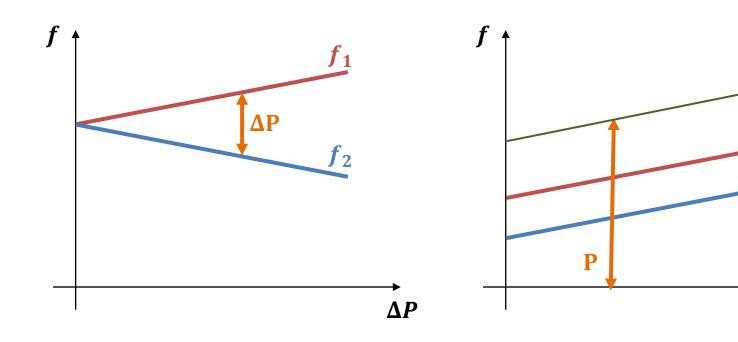
• 
$$f_1 = f_0 + f_P + \Delta f$$

• 
$$f_2 = f_0 + f_P - \Delta f$$

• 
$$f_P \propto P \Rightarrow f_1 + f_2 = 2f_0 + 2f_P \propto P$$

• 
$$\Delta f \propto \Delta P \Rightarrow f_1 - f_2 = 2\Delta f \propto \Delta P$$

## Relationship between pressure and frequency



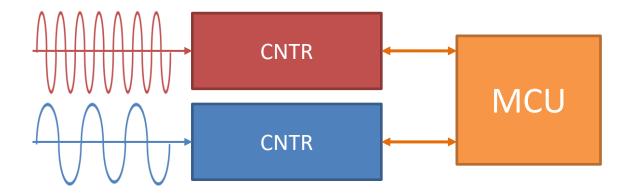
Differential pressure:

$$\Delta P \propto f_1 - f_2$$

Static pressure:

$$P \propto f_1 + f_2$$

### Frequency measurement



- Frequency can be measured by two counters
- No need for ADC (source of significant error)
- Calculations carried out by the microprocessor based on the two measured frequencies

### MEMS resonator pressure sensors

- Measurement range (depending on physical characteristics):
   0.1 20 000 kPa
- Wide span  $(P_{max}/P_{min} \approx 100)$
- Accuracy up to 0.025%
- Long-term stability: 0.1% / 10 év
- Simultaneous measurement of static and differential pressure (necessary for flow and level measurement)
- Direct digital output